



511.40998X00

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicants: N. KOYAMA et al.
Serial No.: 10/018,188
Filed: December 18, 2001
For: CMP ABRASIVE, METHOD FOR POLISHING SUBSTRATE
AND METHOD FOR MANUFACTURING SEMICONDUCTOR
DEVICE USING THE SAME, AND ADDITIVE FOR CMP
ABRASIVE
Group AU: 3724
Examiner: T. Eley
Confirm. No.: 7930

SUBMISSION UNDER 37 CFR §1.114
(AMENDMENT)

Commissioner For Patents
P.O. Box 1450
Alexandria, VA 22313-1450

August 15, 2006

Sir:

In response to the Office Action mailed March 15, 2006, and concurrently with the filing of a Request for Continued Examination (RCE) Transmittal, please amend the above-identified application as listed in the following, and as set forth on the following pages:

Amendments to the Claims; and

Remarks are included following the Amendments.